II. CLAIM AMENDMENTS

1. (Currently Amended) A method of growing semiconductor epitaxial layers on a substrate in a chamber, said method comprising the steps of:

providing a system which includes a substrate,

- providing at least a first growth solution—and optionally one or more further growth solutions, and
- (i) exposing the substrate to the first growth solution, the growth solution being under a supersaturated condition such that a first layer grows on the surface of the substrate; and
- __(ii) optionally exposing the substrate to one or more further growth solutions, the further growth solutions being under a supersaturated condition such that one or more further layers grow on the surface of the first layer; and
- (ii) (iii) uniformly varying the pressure of the system in the chamber by varying the pressure of a non-growth source constituent gas to change the degree of supersaturation of the first growth solution or one or more further growth solutions—to affect the growth of the first layer—or one or more further layers.
- 2. (Currently Amended) A method according to claim 1, further comprising:

- providing the first growth solution and the substrate at atmospheric pressure,
- heating said growth solution to a temperature above its saturation temperature,
- setting <u>athe</u> temperature <u>in the chamberof the system</u> at or below the saturation temperature,
- varying the pressure so as to bring the first growth solution to supersaturation, and
- contacting the substrate with said supersaturated first growth solution so as to deposit material from the growth solution as a solid layer onto the substrate.
- 3. (Currently Amended) A method according to claim 12, further comprising:
 - providing the first growth solution and at least a second growth solution and the substrate at atmospheric pressure,
 - heating each of said growth solutions to a temperature above its saturation temperature,
 - setting thea temperature in the chamber of the system at or below the saturation temperature of each growth solution,
 - varying the pressure of the systemin the chamber so as to bring the first growth solution to supersaturation,

- contacting the substrate with the supersaturated first growth solution in order to deposit material from the first growth solution as a solid layer onto the substrate,
- moving the substrate out of contact with the first growth solution,
- varying the pressure <u>in the chamber of the system</u> so as to change the supersaturation of the second growth solution.

 <u>and</u>
- contacting the substrate with the supersaturated second growth solution in order to deposit material from the second growth solution as a solid layer on the first layer.
- 4. (Currently Amended) A method according to claim 3, further comprising: repeating the steps of moving the substrate out of contact with a growth solution, varying the pressure so as to change the supersaturation of the subsequent growth solution and contacting the substrate with said supersaturated subsequent growth solution in order to deposit material from said subsequent supersaturated growth solution as a solid layer.
- 5. (Currently Amended) A method according to claim 1, further comprising: the steps of providing the first growth solution and the substrate at atmospheric pressure, heating said first growth solution to a temperature above its saturation temperature, setting thea temperature in the chamber of the system at or below the saturation temperature, varying the pressure in the chamber of the system so as to bring the first growth solution to

supersaturation, bringing the substrate into contact with the growth solution and varying the pressure in the chamber of the system whilst material is deposited onto the substrate from the first growth solution as a solid layer.

- 6. (Currently Amended) A method according to claim 12, further comprising:
 - providing the first growth solution and at least a second growth solution and the substrate at atmospheric pressure,
 - heating each of said growth solutions to a temperature above its saturation temperature,
 - setting the temperature in the chamber of the system at or below the saturation temperature of each growth solution,
 - varying the pressure <u>in the chamber of the system</u> so as to bring the first growth solution to supersaturation,
 - first growth solution and varying the pressure in the chamber of the system whilst material is deposited onto the substrate from the first growth solution as a solid layer,
 - moving the substrate out of contact with the first growth solution,
 - varying the pressure <u>in the chamber of the system</u> so as to change the supersaturation of the second growth solution,

- bringing the substrate into contact with the supersaturated second growth solution and varying the pressure whilst material is deposited onto the substrate from the second growth solution as a solid layer.
- 7. (Currently Amended) A method according to claim 6, further comprising:
 - repeating the steps of moving the substrate out of contact with a growth solution, varying the pressure to change the supersaturation of a subsequent growth solution, contacting the substrate with the supersaturated subsequent growth solution and varying the pressure in the chamberof the system whilst material is deposited onto the substrate from the subsequent growth solution as a solid layer.
- 8. (Currently Amended) A method according to claim 1, further comprising wherein the setting a temperature is in the chamber of at least 500°C.
- 9. (Currently Amended) A method according to claim 1, further comprising setting the temperature in the chamber of the system at or below the saturation temperature of the first growth solution and maintaining the temperature essentially constant throughout the method.
- 10. (Currently Amended) A method according to claim 1, wherein said semiconductor epitaxial layers comprise a system which includes III-V semiconductor epitaxial layers.

- 11. (Original) A method according to claim 1 in which the semiconductor epitaxial layers comprise GaSb.
- 12. (New) A method according to claim 1, further comprising the steps of:

providing one or more further growth solutions, and

- (i) exposing the substrate to each of the one or more further growth solutions, the further growth solutions being under a supersaturated condition such that one or more further layers grow on the surface of the first layer; and
- (ii) varying a pressure in the chamber to change the degree of supersaturation of each of the one of more further growth solutions to affect the growth of one or more the further layers.